

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
150V	3.9mΩ@10V	190A

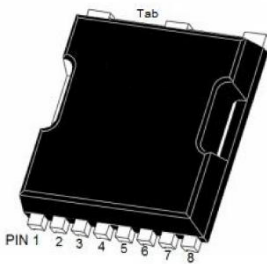
## Feature

- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(on)}$
- Suffix "-Q1" for AEC-Q101

## Application

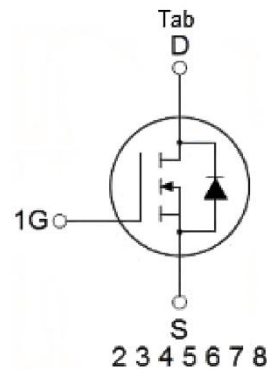
- Power switching application
- Uninterruptible power supply
- DC-DC convertor

## Package

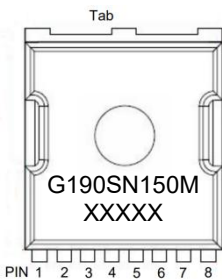


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## Circuit diagram



## Marking



### Absolute maximum ratings (T<sub>C</sub>=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	150	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current <sup>1,3)</sup> (V <sub>GS</sub> =10V, Chip limitation)	I <sub>D</sub>	190	A
Continuous Drain Current <sup>1,3)</sup> (V <sub>GS</sub> =10V, T <sub>C</sub> =100°C)	I <sub>D</sub> (100°C)	134.4	A
Pulsed Drain Current (t <sub>p</sub> ≤10us)	I <sub>DM</sub>	620	A
Single Pulse Avalanche Energy <sup>2)</sup>	E <sub>AS</sub>	1056.25	mJ
Power Dissipation <sup>1,3)</sup>	P <sub>D</sub>	340.9	W
Thermal Resistance Junction to Case	R <sub>θJC</sub>	0.44	°C/W
Operating Junction Temperature	T <sub>J</sub>	-55 ~ +175	°C
Storage Temperature Range	T <sub>STG</sub>	-55 ~ +175	°C

### Electrical characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	150			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =150V, V <sub>GS</sub> =0V			1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	3	3.8	4.6	V
Drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =50A		3.2	3.9	mΩ
<b>Dynamic characteristics<sup>4)</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =75V, V <sub>GS</sub> =0V, f =1MHz		6250		pF
Output Capacitance	C <sub>oss</sub>			1820		
Reverse Transfer Capacitance	C <sub>rss</sub>			23		
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =75V, V <sub>GS</sub> =10V, I <sub>D</sub> =50A		80.3		nC
Gate-Source Charge	Q <sub>gs</sub>			35.1		
Gate-Drain Charge	Q <sub>gd</sub>			19.9		
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DS</sub> =75V, V <sub>GS</sub> =10V, I <sub>D</sub> =50A R <sub>G</sub> =3Ω		31.7		nS
Turn-on rise time	t <sub>r</sub>			77.4		
Turn-off delay time	t <sub>d(off)</sub>			40.4		
Turn-off fall time	t <sub>f</sub>			7.79		
<b>Source-Drain Diode characteristics</b>						
Diode Forward Current	I <sub>S</sub>	T <sub>C</sub> =25°C			190	A
Diode Forward voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =50A			1.2	V
Reverse Recovery Time	T <sub>rr</sub>	V <sub>GS</sub> =0V, V <sub>R</sub> =75V, I <sub>F</sub> =50A di/dt =-100A/μs		73.3		nS
Reverse Recovery Charge	Q <sub>rr</sub>				176.3	

Notes:

- 1) The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2) The test condition is T<sub>J</sub> =25°C, V<sub>G</sub>=10V, L=0.5mH, R<sub>G</sub> =25Ω, I<sub>AS</sub>=65A.
- 3) Thermal resistance from junction to soldering point (on the exposed drain pad).
- 4) Guaranteed by design, not subject to production.

## Typical Characteristics

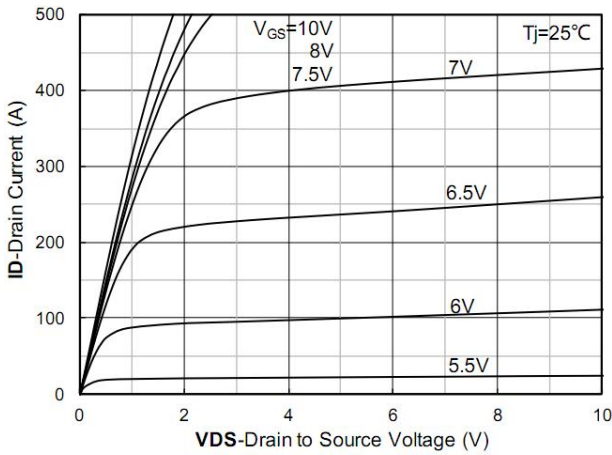


Figure 1. Output Characteristics; typical values

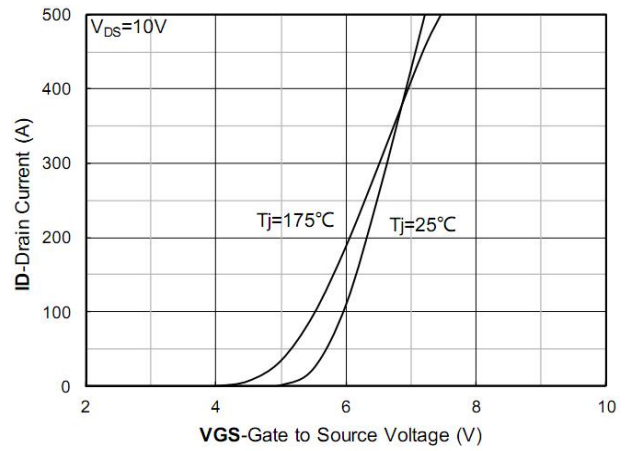


Figure 2. Transfer Characteristics; typical values

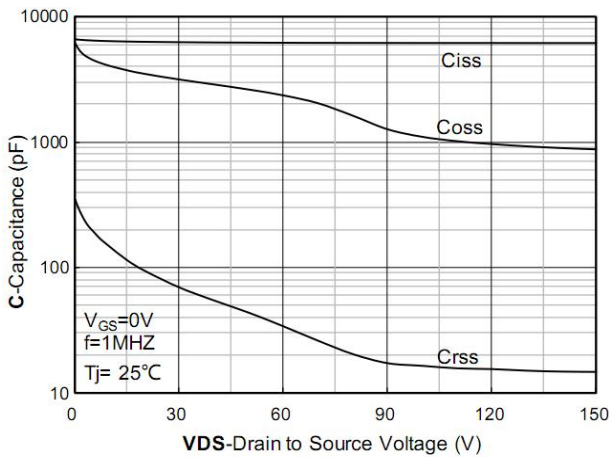


Figure 3. Capacitance Characteristics; typical values

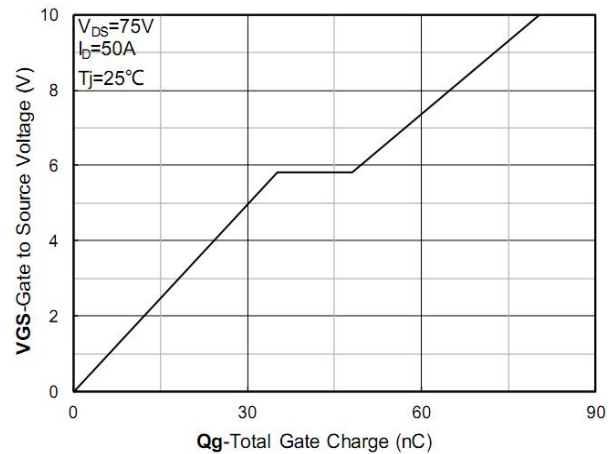


Figure 4. Gate Charge; typical values

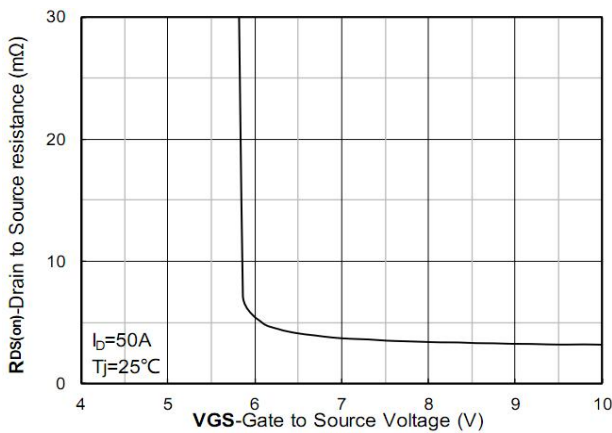


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

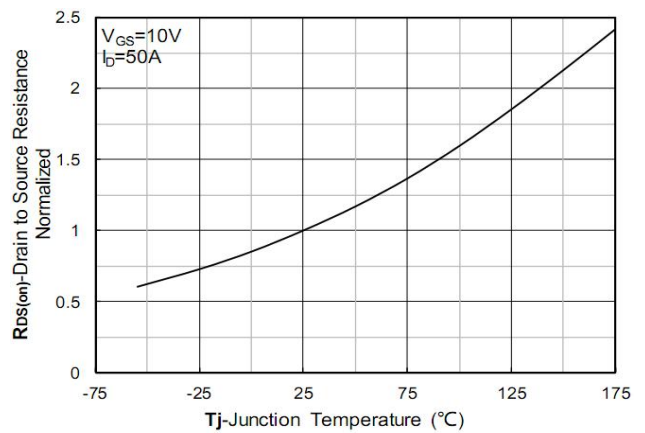


Figure 6. Normalized On-Resistance

## Typical Characteristics

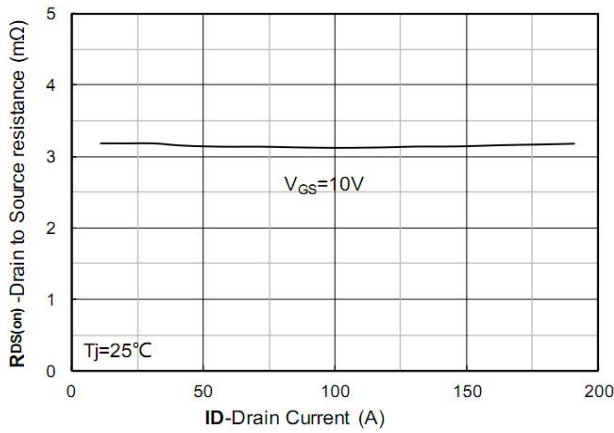


Figure 7.  $R_{DS(on)}$  vs. Drain Current; typical values

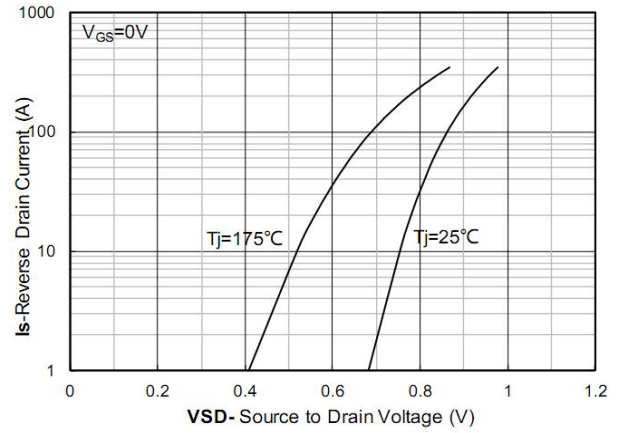


Figure 8. Forward characteristics of reverse diode; typical values

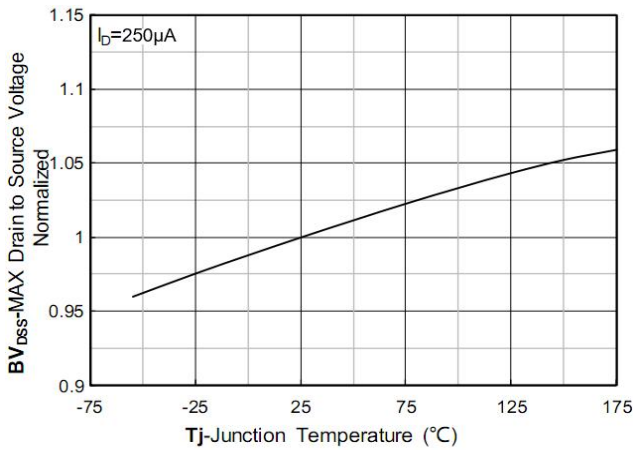


Figure 9. Normalized breakdown voltage

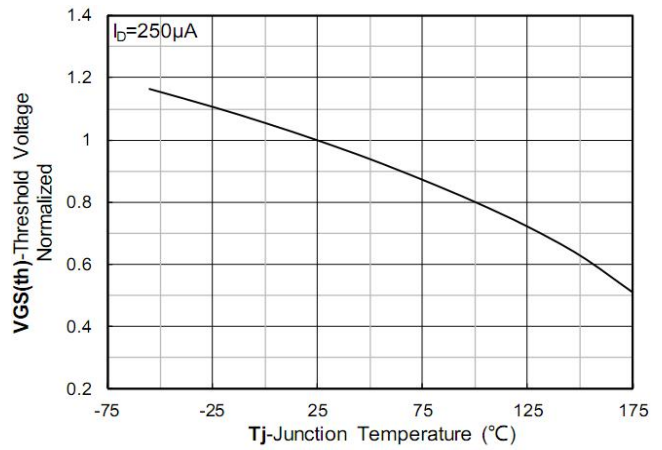


Figure 10. Normalized Threshold voltage

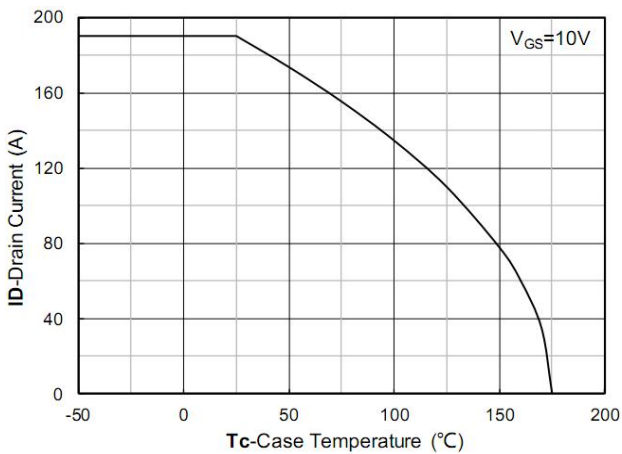


Figure 11. Current dissipation

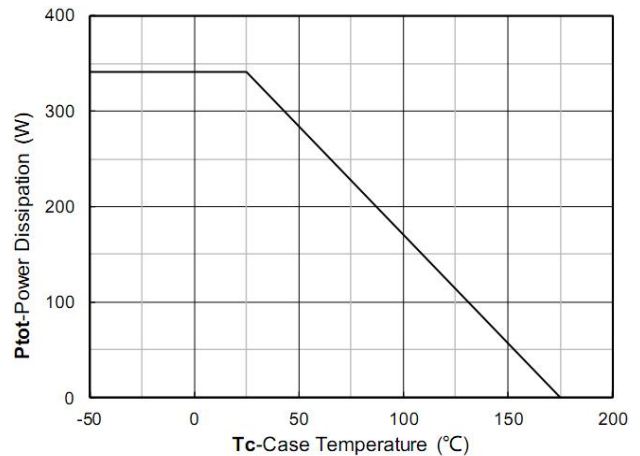


Figure 12. Power dissipation

## Typical Characteristics

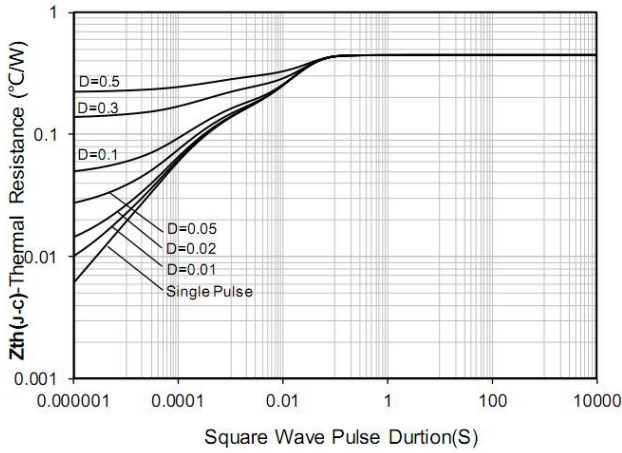


Figure 13. Maximum Transient Thermal Impedance

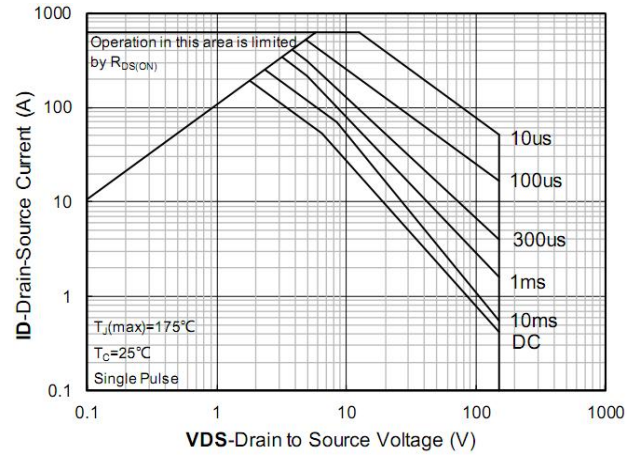
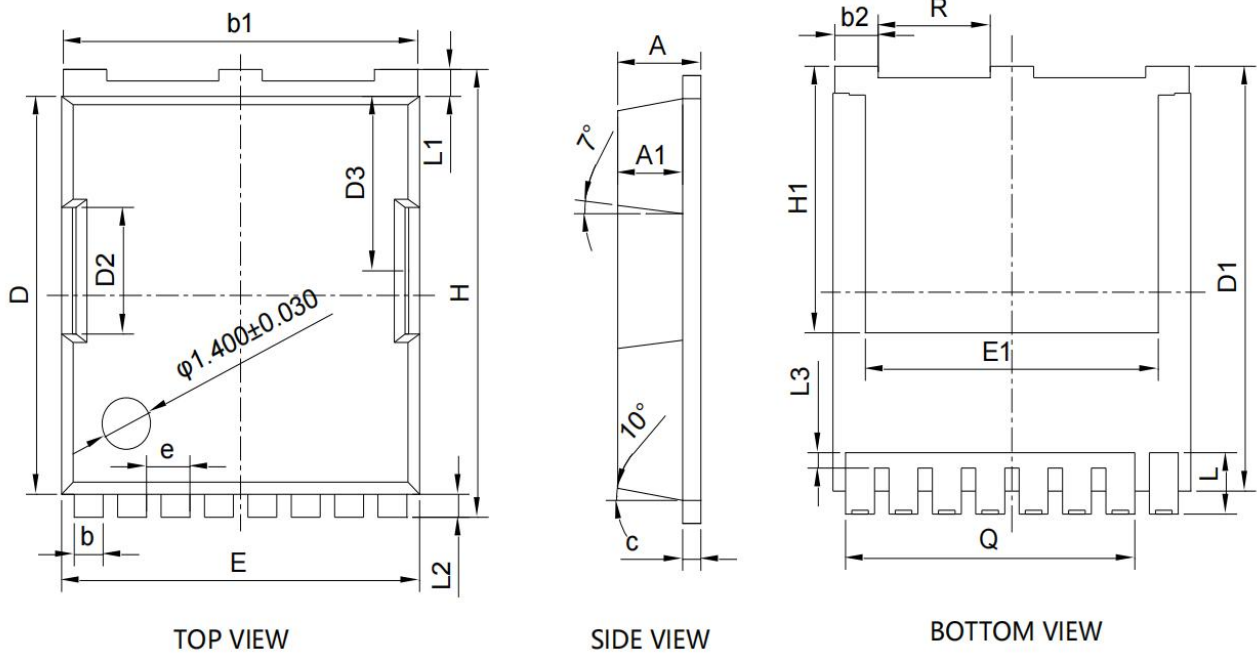


Figure 14. Safe Operation Area

### TOLL Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	1.700	1.900	0.067	0.075
b	0.700	0.900	0.028	0.035
$b_1$	9.700	9.900	0.382	0.390
$b_2$	1.100	1.300	0.043	0.051
c	0.400	0.600	0.016	0.024
D	10.280	10.480	0.405	0.413
D1	10.980	11.180	0.432	0.440
D2	3.200	3.400	0.126	0.134
D3	4.450	4.650	0.175	0.183
E	9.800	10.000	0.386	0.394
E1	8.000	8.200	0.315	0.323
e	1.200 BSC.		0.047 BSC.	
H	11.580	11.780	0.456	0.464
H1	6.950 BSC.		0.274 BSC.	
L	1.500	1.700	0.059	0.067
L1	0.600	0.800	0.024	0.031
L2	0.500	0.700	0.020	0.028
L3	0.300	0.500	0.012	0.020
Q	8.000 REF.		0.315 REF.	
R	3.000	3.200	0.118	0.126